PCN Numb	PCN Number: 20230613000.1A PCN Date: June 27, 2023								27, 2023				
Title:         Qualification of TI Clark as an alternate Assembly site for select devices							<u> </u>						
Customer Contact:         PCN Manager         Dept:         Quality Services													
Proposed 1 <sup>st</sup> Ship Date: Sept			ot 11, 2023			Sample Requests accepted until							
*Sample r	*Sample requests received after July 13, 2023 will not be supported.												
Change Ty													
	bly Site					Design Wafer Bump M							
	nbly Pro Noly Mat					Data Sheet Wafer Bump Pr				SS			
	nical S		ation		$\exists$	Part number changeWafer Fab SiteTest SiteWafer Fab Materi			d .				
	inical S	•				Test Process 🔲 Wafer Fab Proces							
	<u> </u>	,		5				etails					
Descriptio													
Revision A	<mark>l</mark> is to d	docum	<mark>ent t</mark>	he proj	per A	<mark>Assemb</mark>	<mark>ly s</mark>	<mark>ite in all areas</mark>	of t	<mark>he lette</mark>	r.		
Texas Instruments Incorporated is announcing the qualification of CDAT <b>TI Clark</b> as an additional Assembly site for the devices listed below. There are no construction differences between the 2 sites.													
Reason fo	r Chan	ge:											
Supply con	ntinuity												
Anticipate	ed impa	act on	For	m, Fit,	Fun	ction,	Qu	ality or Reliat	oility	(positi	ve / ı	negativ	ve):
None													
Impact on	Enviro	onme	ntal I	Rating	S								
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
RoHS RE		REACH			Green St	atus		IEC 62474		'4			
🛛 No Cha	ange		$\boxtimes$	No Cha	ange	ge 🛛 🛛 No Change			$\square$	🛛 No Change			
Changes t	Changes to product identification resulting from this PCN:												
Assembly	/ Site	As	semb	(22L)	Orig	in	Assembly Country Code (23L)			le	Assembly City		
JCAF	>			JCP	СР			CHN	CHN		Jiangyin		n
Clark QAB				PHL				Angeles City, Pampanga					
Sample product shipping label (not actual product label) TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 (not actual product label) (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS													

Product Affected:			
AFE4420YZR	AFE49I30YZR	CSD68835F5	INA186A2IYFDR
AFE4420YZT	AFE49I30YZT	CSD68836F5	INA186A3IYFDR
AFE4432YCHR	CSD17484F4	CSD83325L	INA186A4IYFDR
AFE4432YCHT	CSD17484F4T	CSD83325LT	INA186A5IYFDR
AFE44I30YZR	CSD25484F4	CSD85302L	INA191A1IYFDR
AFE44I30YZT	CSD25484F4T	CSD85302LT	SN1805031YZR
AFE44S30YZR	CSD58897L	CSD87501L	SN1901046YZR
AFE44S30YZT	CSD58898F4	CSD87501LT	TPS22913CYZVR
AFE4900YZR	CSD58903F3	DRV2604YZFR	TPS22913CYZVT
AFE4900YZT	CSD58905F5	INA186A1IYFDR	



**TI Information** Selective Disclosure

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>TMP144YMTR</u>		
PC	Precon Level 1	MSL1, 260C	3/720/0		
ELFR	Early Life Failure Rate, 150C	24 Hours	3/3024/0		
HTOL	Life Test, 150C	300 Hours	3/231/0		
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0		
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0		
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0		
HTSL	High Temp Storage Bake, 150C	1000 Hour	3/231/0		
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0		
HBM	ESD - HBM	2000 V	3/9/0		
CDM	ESD - CDM	1000 V	3/9/0		
LU	Latch-up	(Per JESD78)	3/18/0		
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass		
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass		
SD	Pb Free Solderability - Dip and Look	Pb Free/Solderability	3/36/0		
SD	Pb Solderability - Dip and Look	Pb/Solderability	3/36/0		

QBS: Qual By Similarity
Qual Device TMP144YMTR is qualified at LEVEL1-260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free (SMT) and Green

TI Qualification ID: 20200805-135627



## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TA \$2552YFF	Qual Device: TAS2553YFF	
CDM	ESD - CDM	1500 V	-	3/9/0	
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/3000/0	
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	
HBM	ESD - HBM	1500 V	-	3/9/0	
HBM	ESD - HBM	2000 V	-	3/9/1	
HBM	ESD - HBM	2500 V	-	3/9/0	
HBM	ESD - HBM	3000 V	-	3/9/0	
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	
HTSL	High Temp Storage Bake 170C	420 Hours	3/228/0	-	
LU	Latch-up	(Per JESD78)	-	3/18/0	
SBS	Bump-shear	Solder Balls	3/108/0	-	
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	-	
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/228/0	-	

- QBS: Qual By Similarity

- Qual Device TAS2553YFF is qualified at LEVEL1-260C

- Qual Device TAS2552YFF is qualified at LEVEL1-260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20141010-108724

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail				
WW Change Management Team	PCN ww admin team@list.ti.com				

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